### **LN69**

### GaAs Infrared Light Emitting Diode

For optical control systems

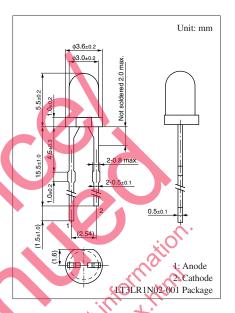
#### ■ Features

- High-power output, high-efficiency:  $I_e = 3.5 \text{ mW/sr (min.)}$
- Emitted light spectrum suited for silicon photodetectors
- Good radiant power output linearity with respect to input current
- Long lifetime, high reliability
- \$\phi 3 plastic package

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V <sub>R</sub>	3	V
Forward current	$I_{F}$	50	mA
Pulse forward current *	$I_{FP}$	1	A
Power dissipation	P <sub>D</sub>	75	mW
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C
Storage temperature	T <sub>stg</sub>	-40 to +100	°C

Note) \*: f = 100 Hz, Duty Cycle = 0.1%

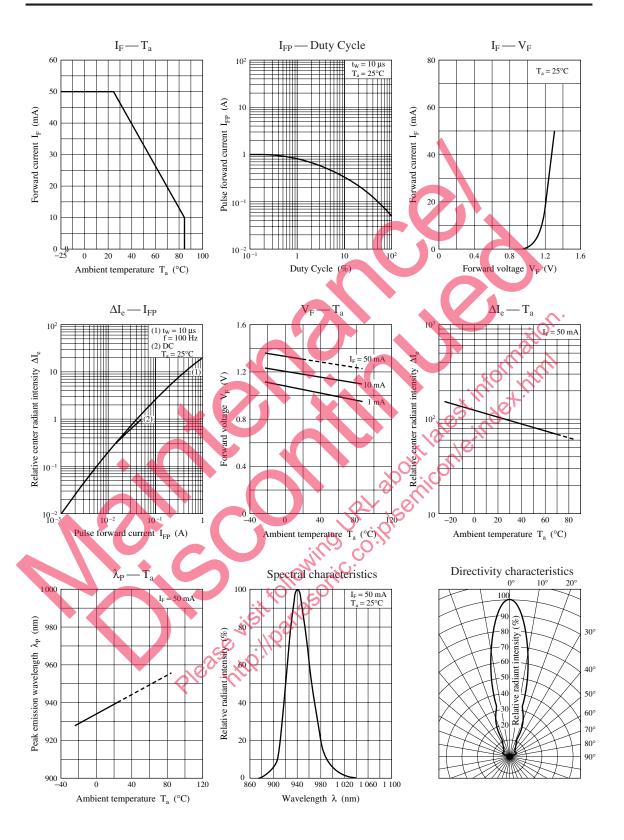


### ■ Electrical-Optical Characteristics T<sub>a</sub> = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 50 \text{ mA}$		1.3	1.5	V
Reverse current	$I_R$	$V_R = 3 V$			10	μΑ
Center radiant intensity	$I_{e}$	$I_F = 20 \text{ mA}$	3.5			mW/sr
Peak emission wavelength	λ	I <sub>F</sub> = 50 mA		940		nm
Spectral half band width	ON X	$I_F = 50 \text{ mA}$		50		nm
Terminal capacitance	Ct	$V_R = 0 \text{ V, f} = 1 \text{ MHz}$		35		pF
Half-power angle	θ	The angle when the radiant power is halved		15		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 1 MHz 
$$f_C: 10 \times log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$



# Caution for Safety

# **⚠ DANGER**

■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded form general industrial waste or household garbage.

## Request for your special attention and precautions in using the technical information and semiconductors described in this material

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